PCN Number:	20170906000	**PCN Date:**	Sept 7, 2017
Title:	Qualification of additional Fab site (DMOS6) and Assembly/Bump site (JCAP) option for select devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Dec 7, 2017	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☒	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of an additional fab (DMOS6) and assembly/bump (JCAP) site for the selected devices listed in "Product Affected" section.

Current Fab Site				Additional Fab Site			
Fab Site	**Process**	**Bump Site**	**Wafer Diameter**	**Fab Site**	**Process**	**Bump Site**	**Wafer Diameter**
RFAB	LBC8	Clark-BP	300 mm	DMOS6	LBC8	JCAP-BP	300 mm

There are no material difference between devices currently manufactured and devices built with this manufacturing option.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

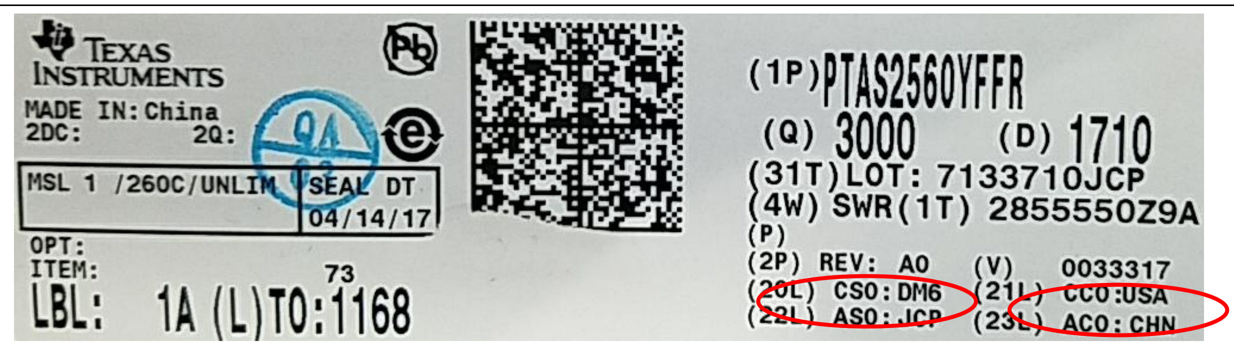
Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
DMOS6	**DM6**	**USA**	**Dallas**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
Clark	QAB	THA	Bangkok
JCAP	**JCP**	**CHN**	**Jiangyin**

Sample product shipping label (not actual product label)



Topside Device marking (if included):
Assembly site code for QAB= I
Assembly site code for JCP = W

Product Affected:

TAS2560YFFR	TAS2560YFFT

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

Qualification Report

TAS2560YFF WCSP Device Qual (DMOS6/JCAP)
Approve Date 18-Aug-2017

Product Attributes

Attributes	Qual Device: TAS2560YFF	QBS Product Reference: TAS2560YFF	QBS Process Reference: TAS2552YFF	QBS Process Reference: TAS2553YFF	QBS Package Reference: CD3230A0YFF
Wafer Fab Supplier	DMOS6	RFAB	RFAB/DMOS6	RFAB/DMOS6	RFAB
Wafer Process	LBC8LV	LBC8LV	LBC8LV	LBC8LV	LBC7
Assembly Site	JCAP	CLARK-AT	CLARK-AT	CLARK-AT	JCAP
Package Family	DSBGA	DSBGA	DSBGA	DSBGA	DSBGA

- QBS: Qual By Similarity
- Qual Device TAS2560YFF is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TAS2560YFF	QBS Product Reference: TAS2560YFF	QBS Process Reference: TAS2552YFF	QBS Process Reference: TAS2553YFF	QBS Package Reference: CD3230A0YFF
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	Pass	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	3/3000/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	1/77/0
HBM	ESD - HBM	4000 V	1/3/0	1/3/0	-	3/9/0	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	-	3/9/0	-
HTOL	Life Test, 125C	1000 Hours	1/77/0	-	-	3/231/0	1/77/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	3/228/0	-	3/231/0
LU	Latch-up	(Per JESD78)	1/6/0	1/6/0	-	3/18/0	-
PD	Physical Dimensions	--	-	-	-	-	3/15/0
SBS	Bump-shear	--	1/50/0	-	3/108/0	-	3/150/0
TC	Temperature Cycle, -55/125C	700 Cycles	1/77/0	-	3/231/0	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	-	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	3/228/0	-	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

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